



PRESS RELEASE

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Chiplets: A Key Enabler for the Next 10-20 Years

Continued monolithic integration is expensive and can suffer from the defect density yield loss associated with large die. As a result, an increasing number of companies are turning to new architectures using chiplets to achieve the economic advantages lost with expensive monolithic scaling. TechSearch International's new Advanced Packaging Update (APU) details many advantages of chiplets and provides examples in production today as well as a preview of future end products. The report also provides an update on embedded bridge developments and a forecast for high bandwidth memory (HBM).

TechSearch International's new report peeks inside Apple's latest iPhone with a count of the wafer level packages (WLPs) and finds a surprising amount of underfill. Quarterly and annual OSAT financial trends are examined. The latest APU is a 45-page report with full references and an accompanying set of 52 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on twitter @Jan_TechSearch and on LinkedIn (TechSearch International).